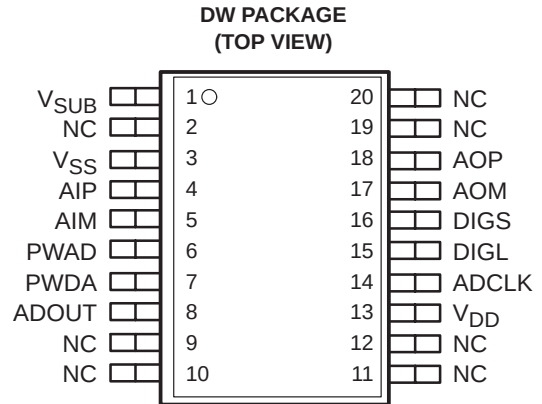


- Analog Portion of ADC and DAC for Audio-Band Signal-Processing Applications
- 5-V Supply Voltage
- Oversampling Second-Order Sigma-Delta Modulator
- 1.024-MHz Master Clock Frequency
- On-Chip Continuous-Time Antialiasing and Smoothing Filters
- High-Performance Fully Differential and Symmetrical Analog Data Paths
- Internal Reference Voltage and Common-Mode Bias Voltage Generation
- Very Low Power Consumption Mode



NC – No internal connection

description

The MSP58C20 is the analog portion of an audio-band sigma-delta analog-to-digital and digital-to-analog converter and is a companion part to the MSP58C80. The MSP58C20 is designed to operate only with the MSP58C80, which contains the digital portion of the audio-band converter. The circuit consists of three main blocks: the analog-to-digital converter (ADC), the digital-to-analog converter (DAC), and internal reference and bias voltages.

The analog-to-digital conversion chain consists of a continuous-time antialiasing stage, an analog oversampled modulator, and the modulator bias voltage. The antialiasing stage is a second-order low-pass filter with a cutoff frequency of typically 190 kHz. The modulator is a sigma-delta feedback loop, which oversamples the signal at 1.024 MHz and provides second-order noise shaping. It performs the conversion of the differential analog input signal to a pulse-density-modulated single-bit digital output (ADOUT). When a maximum positive differential input voltage (i.e., a maximum positive voltage difference of AIP – AIM) is applied at the AIP and AIM inputs, the resulting code at the ADOUT output is all ones.

The digital-to-analog conversion chain consists of a fast DAC, an analog low-pass filter, and the filter's bias voltage. The two input bits (DIGS and DIGL), sampled at 0.512 MHz from a digital modulator on the MSP58C80, are the inputs of the DAC conversion chain. Based on the values for DIGS (the sign bit) and DIGL (the level bit), the following table shows the DAC voltage steps that are produced.

DIGS	DIGL	DAC VOLTAGE STEPS
L	L	$-1 \times V_{ref}$
L	H	$-2 \times V_{ref}$
H	L	$+1 \times V_{ref}$
H	H	$+2 \times V_{ref}$

When DIGS = L, the AOM analog output has a more positive voltage than AOP. When DIGL = H, the absolute value of the voltage difference between AOP and AOM is greater than when DIGL = L. A band-gap voltage source is used to produce the DAC and ADC reference voltages. These two references are different to avoid crosstalk between the two converters.



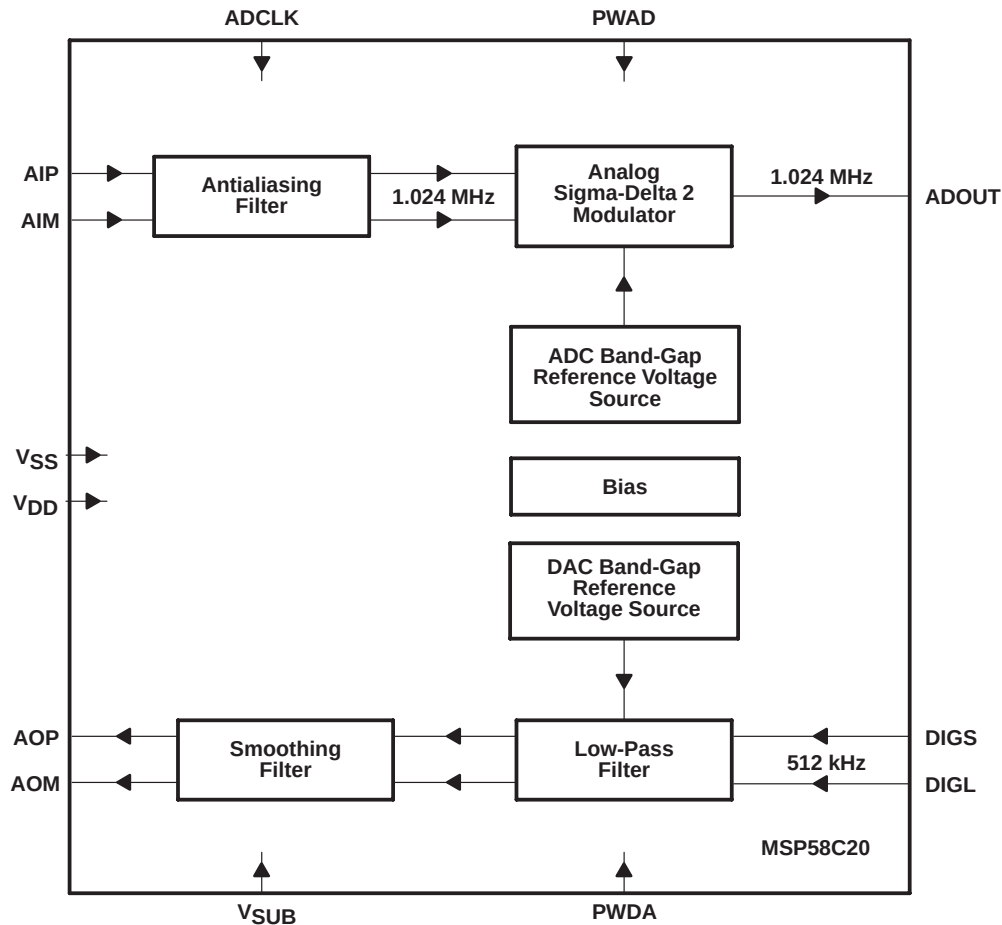
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

MSP58C20
AUDIO-BAND CONVERTER

SPSS005B-11 MSP58C20 110511B 0006

查询"MSP58C20SDW"数据手册

functional block diagram



Terminal Functions

TERMINAL NAME	NO.	A/D	I/O	DESCRIPTION
ADCLK	14	D	I	ADCLK is a 1.024-MHz clock input.
ADOUT	8	D	O	ADOUT is the 1-bit output of the ADC modulator and is sampled at 1.024 MHz.
AIM	5	A	I	AIM is a negative differential input for the ADC. AIP and AIM together form a balanced differential input. The biasing of this terminal is fixed through resistors by the internal common-mode voltage source. This terminal can be ac coupled or dc coupled. If the terminal is dc coupled, external common-mode bias should satisfy recommended operating conditions.
AIP	4	A	I	AIP is a positive differential input for the ADC. AIP and AIM together form a balanced differential input. The biasing of this terminal is fixed through resistors by the internal common-mode voltage source. This terminal can be ac coupled or dc coupled. If the terminal is dc coupled, external common-mode bias should satisfy recommended operating conditions.
AOM	17	A	O	AOM is a negative differential DAC output. AOP and AOM together form a balanced differential output. The common-mode voltage at this terminal is fixed by the internal common-mode circuitry.
AOP	18	A	O	AOP is a positive differential DAC output. AOP and AOM together form a balanced differential output. The common-mode voltage at this terminal is fixed by the internal common-mode circuitry.
DIGL	15	D	I	DIGL is the input level bit of the DAC and is sampled at 0.512 MHz.
DIGS	16	D	I	DIGS is the input sign bit of the DAC and is sampled at 0.512 MHz.
PWAD	6	D	I	When PWAD is high, it puts the ADC part of the circuit into a power-down mode. When both PWAD and PWDA are high, the MSP58C20 is in a stable low-power-consumption state.
PWDA	7	D	I	When PWDA is high, it puts the DAC part of the circuit in a power-down mode. When both PWAD and PWDA are high, the MSP58C20 is in a stable low-power-consumption state.
V _{SUB}	1	n/a	n/a	V _{SUB} and V _{SS} must be connected together to minimize substrate currents during power up, power down, and normal operation.
V _{DD}	13	n/a	n/a	V _{DD} is the 5-V power supply.
V _{SS}	3	n/a	n/a	V _{SS} is ground. The internal band-gap voltage and the common-mode bias voltages are referenced to V _{SS} .

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{DD} (see Note 1)	–0.3 V to 6 V
Input voltage range, V _I (any digital or analog input, see Note 1)	–0.3 V to V _{DD} + 0.3 V
V _{SUB} , V _{SS} voltage range, relative to each other	–30 mV to 30 mV
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to V_{SS} unless otherwise noted.

MSP58C20
AUDIO-BAND CONVERTER

SPSS043B-11 MSP58C20S10W 1155E 01/06

查询"MSP58C20S10W"供应商

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD} (see Note 1)	4.75	5	5.25	V
High-level input voltage, digital inputs, V_{IH} (see Note 1)	2			V
Low-level input voltage, digital inputs, V_{IL} (see Note 1)			0.8	V
Maximum differential input voltage between AIP and AIM (ac or dc peak-to-peak voltage), V_{ID}	-3		3	V
Common-mode input voltage at AIP and AIM, V_{IC} (see Note 1)	$0.45 \times V_{DD}$	$0.5 \times V_{DD}$	$0.55 \times V_{DD}$	V
Input clock frequency, ADCLK		1.024		MHz
Resistive load between AOP and AOM	15			k Ω
Capacitive load at AOP and AOM (at each output versus V_{SS})			50	pF
Operating free-air temperature, T_A	0		70	$^{\circ}\text{C}$

NOTE 1: All voltage values are with respect to V_{SS} unless otherwise noted.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature, ADCLK input frequency = 1.024 MHz, PWDA = L and PWAD = L (power-up mode) (unless otherwise noted)

supply current characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{DD} Supply current	PWAD = H, PWDA = H, Digital inputs = V_{DD} or V_{SS} , Digital output = no load			50	μA
	PWAD = L, PWDA = L	6.5	9	16	mA

analog input characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Transmit dynamic range, maximum differential input voltage (between AIP and AIM)	dc or ac voltage	± 2.22	± 2.36	± 2.5	V
V_{IO} Transmit differential input offset voltage	See Note 2	-150		150	mV
V_{IC} Internal common-mode voltage at AIP and AIM		$0.4 \times V_{DD}$	$0.5 \times V_{DD}$	$0.6 \times V_{DD}$	V
z_i Input impedance	AIP Between AIP and internal common-mode voltage source (AIM = $V_{DD}/2$)	15	25	35	$k\Omega$
	AIM Between AIM and internal common-mode voltage source (AIP = $V_{DD}/2$)	15	25	35	
Input capacitance	AIP Measured at 5 MHz between AIP and V_{SS} (AIM = $V_{DD}/2$)			50	pF
	AIM Measured at 5 MHz between AIM and V_{SS} (AIP = $V_{DD}/2$)			50	

NOTE 2: Calculated by linear regression based on five dc measurements between -1 V and 1 V

digital output characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH} Digital high-level output voltage versus V_{SS}	$I_{OH} = 300 \mu A$	2.4			V
V_{OL} Digital low-level output voltage versus V_{SS}	$I_{OL} = 1 mA$			0.4	V

analog output characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OD} Differential output voltage, dynamic range, AOP to AOM	Balanced loads, dc measurement	± 2.82	± 3	± 3.18	V
V_{OO} Differential output offset voltage	dc measurement	-150		150	mV
V_{OC} Common-mode output voltage at AOP and AOM		$0.4 \times V_{DD}$	$0.5 \times V_{DD}$	$0.6 \times V_{DD}$	V

MSP58C20

AUDIO-BAND CONVERTER

SPSS033B-1 MSP58C20S10W 06

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature, ADCLK input frequency = 1.024 MHz, PWDA = L and PWAD = L (power-up mode) (unless otherwise noted) (continued)

ADC transmit characteristics[†]

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
Transmit absolute gain tolerance	$V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, Input = 1-kHz sine wave at -13 dBrl				± 0.5	dB
Transmit gain versus input level	Input = 1-kHz sine wave, Gain reference level = gain measured at input level of -13 dBrl , See Note 3	Input level = -1 dBrl to -43 dBrl			± 0.25	dB
		Input level = -43 dBrl to -53 dBrl			± 0.5	
		Input level = -53 dBrl to -58 dBrl			± 1	
Transmit gain versus supply voltage	$V_{DD} = 4.75\text{ V}$ to 5.25 V , Input = 1 kHz at -13 dBrl				± 0.15	dB
Transmit idle channel in-band noise	Psophometrically-weighted output noise, Transmit channel idle			-76		dBrlp
Transmit idle channel single-frequency noise spectrum (see Note 4)	$T_A = 25^\circ\text{C}$, FFT rectangular window bandwidth = 125 Hz, Transmit channel idle, See Figure 5	$f = 50\text{ Hz}$		-80		dBrl
		$f = 300\text{ Hz}$		-82		
		$f = 3.4\text{ kHz}$		-82		
		$f = 4\text{ kHz}$		-80		
		$f = 7\text{ kHz}$		-72		
		$f = 12\text{ kHz}$		-65		
		$f = 20\text{ kHz}$		-64		
Transmit single-frequency distortion	Input = one frequency in 0.7-kHz to 1.1-kHz band at -4 dBrl , Measured first two harmonics				-50	dB
Transmit intermodulation distortion (see Note 4)	Input = two frequencies in 0.3-kHz to 3.4-kHz band, Input levels = -7 dBrl and -24 dBrl , Measured second and third intermodulation products				-40	dBrl
Transmit-signal-to-total-noise-plus-distortion ratio (see Note 5)	$V_{DD} = 5.25\text{ V}$, $T_A = 25^\circ\text{C}$, Input = 1-kHz sine wave, Measured psophometrically-weighted total noise plus distortion, See Figure 6	Input level = -70 dBrl	-13			dB
		Input level = -20 dBrl	50			
		Input level = -1 dBrl	50			
Transmit gain variations versus input frequency (see Notes 4 and 6)	$f = 0.1\text{ kHz}$ to 4 kHz , Input level = -13 dBrl				± 0.6	dB
Transmit power supply rejection	See Note 7			30		dB
I_{lkg} Leakage current	Voltage applied to terminal is between V_{SS} and V_{DD} , PWDA = H (power-down mode)	AIP	-10		10	μA
		AIM	-10		10	
Receive-to-transmit crosstalk	Receive input = one frequency in 0.3-kHz to 3.4-kHz band at -3 dBrl , Crosstalk measured at transmit digital output, Transmit channel idle				-70	dB

[†] This table contains specifications in which the power levels are expressed in dBrl; dBrl stands for dB above reference level. 0 dBrl is the ADC theoretical overload point. This overload point corresponds to a sine wave at the input of the modulator with peak amplitude equal to 2.25 V dBrlp is a psophometrically-weighted value being compared against a psophometrically-weighted reference.

NOTES: 3. Input satisfies CCITT G.714 15.3, Method 2.

4. This parameter is characterized but not tested.

5. Input satisfies CCITT G.714 14.3, Method 2.

6. Gain is relative to gain at 1 kHz.

7. The power-supply rejection measurement is made with a 50-mVrms, 0- to 20-kHz signal applied to V_{DD} and with the transmit channel idle.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature, ADCLK input frequency = 1.024 MHz, PWDA = L and PWAD = L (power-up mode) (unless otherwise noted) (continued)

DAC receive characteristics†

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
Receive gain tolerance	$V_{DD} = 5\text{ V}$, Input = 1-kHz sine wave at -28 dBrl				± 0.5	dB
Receive gain versus input level	Input = 1-kHz sine wave, Gain reference level = gain measured at input level of -28 dBrl , See Note 8	Input level = -1 dBrl to -43 dBrl			± 0.25	dB
		Input level = -43 dBrl to -53 dBrl			± 0.5	
		Input level = -53 dBrl to -58 dBrl			± 1	
Receive gain versus supply voltage	$V_{DD} = 4.75\text{ V}$ to 5.25 V , Digital input = 1-kHz sine wave at -28 dBrl				± 0.15	dB
Receive idle channel in-band noise	Receive channel idle, Psophometrically-weighted output noise			-75		dBrlp
Receive idle channel single-frequency noise spectrum (see Note 4)	$T_A = 25^\circ\text{C}$, Receive channel idle, Measurement bandwidth = 125 Hz , See Figure 6	$f = 100\text{ Hz}$		-82		dBrl
		$f = 3\text{ kHz}$		-82		
		$f = 10\text{ kHz}$		-64		
		$f = 100\text{ kHz}$		-64		
Receive single-frequency distortion	Input = one frequency in 0.7-kHz to 1.1-kHz band at -6 dBrl , Measured first two harmonics				-50	dB
Receive intermodulation distortion (see Note 4)	Input = two frequencies in 0.3-kHz to 3.4-kHz band, Input levels = -7 dBrl and -24 dBrl , Measured second and third intermodulation products				-40	dBrl
Receive signal-to-total-noise-plus-distortion ratio (see Note 9)	$V_{DD} = 5.25\text{ V}$, $T_A = 25^\circ\text{C}$, Input = 1-kHz sine wave, Measured psophometrically-weighted total noise plus distortion, See Figure 7	Input level = -70 dBrl		0		dB
		Input level = -20 dBrl		50		
		Input level = -1 dBrl		50		
Receive gain variations versus input sine wave frequency (see Note 6)	$V_{DD} = 4.75\text{ V}$, $T_A = 25^\circ\text{C}$, Input level = -13 dBrl , See Figure 9	$f = 156\text{ Hz}$ to 4 kHz		$-0.6^\ddagger$	0.6	dB
		$f = 4.6875\text{ kHz}$		-0.7	-0.4	
		$f = 6.25\text{ kHz}$		-1.75	-1.4	
		$f = 7.8125\text{ kHz}$		-3.35	-2.9	
		$f = 9.375\text{ kHz}$		-5.25	-4.8	
		$f = 10.9375\text{ kHz}$		-7.25	-6.8	
		$f = 12.5\text{ kHz}$		-9.2	-8.7	
Receive gain variations versus input sine wave frequency (see Note 6)	$V_{DD} = 4.75\text{ V}$, $T_A = 25^\circ\text{C}$, Input level = -13 dBrl , See Figure 9	$f = 15.625\text{ kHz}$		-12.8	-12.2	dB
Receive power supply rejection	See Note 10			30		dB

† This table contains specifications in which the power levels are expressed in dBrl; dBrl stands for dB above reference level. 0 dBrl is the DAC overload point. Overload levels of the digital modulator (see parameter measurement information) are 32767 and -32767 peak values. The 0-dBrl level is related to maximum differential output voltage, which is typically 2.25 V.

‡ The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for receive gain variations versus input sine-wave frequency.

NOTES: 4. This parameter is characterized but not tested.

6. Gain is relative to gain at 1 kHz.

8. Input satisfies CCITT G.714 15.4 Method 2.

9. Input satisfies CCITT G.714 14.4 Method 2.

10. The power supply rejection measurement is made with a 50-mVrms, 0-kHz to 20-kHz signal applied to V_{DD} and with the receive channel idle.

MSP58C20

AUDIO-BAND CONVERTER

SPSS043B-1145 MSP58C20S10V115 SE (Rev. 10/96)

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature, ADCLK input frequency = 1.024 MHz, PWDA = L and PWAD = L (power-up mode) (unless otherwise noted) (continued)

DAC receive characteristics (continued)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{lkg} Leakage current	AOP	-10		10	μA
	AOM	-10		10	
Output impedance, differential, between AOP and AOM (see Note 4)		30			kΩ
Transmit-to-receive crosstalk	Transmit input = one frequency in 0.3-kHz to 3.4-kHz band at -3 dB _I , Receive channel idle, Crosstalk measured at receive analog output			-70	dB

NOTE 4. This parameter is characterized but not tested.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{su1} Transmit setup time at power up (PWAD transition from H to L)	ADCLK input frequency = 1.024 MHz, See Note 11		20		μs
t _{su2} Receive setup time at power up (PWDA transition from H to L)	ADCLK input frequency = 1.024 MHz, See Note 12		20		μs
t _{su3} Receive setup time, DIGS or DIGL setup before ADCLK↑	See Figure 4	50			ns
t _h Receive hold time, DIGS or DIGL hold after ADCLK↑	See Figure 4	50			ns
t _c Cycle time, ADCLK			1		μs
t _{w1} Pulse duration, ADCLK high		470			ns
t _{w2} Pulse duration, ADCLK low		470			ns
t _f Fall time, ADCLK				20	ns
t _r Rise time, ADCLK				20	ns

NOTES: 11. After the setup time, the transmit channel displays normal operating characteristics.

12. After the setup time, the receive channel displays normal operating characteristics.

switching characteristic over recommended ranges of supply voltage and operating free-air temperature

PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
t _a Transmit access time, ADOUT after ADCLK↑ (see Note 4)	See Figure 3			100	ns

NOTE 4. This parameter is characterized but not tested.



PARAMETER MEASUREMENT INFORMATION

The receive characteristics in the electrical characteristics table are measured by activating the MSP58C20 receive path through a digital modulator. This modulator consists of two functional blocks (see Figure 1 and Figure 2) connected in series. The output of the decoder (see Figure 2) is shown in Table 1.

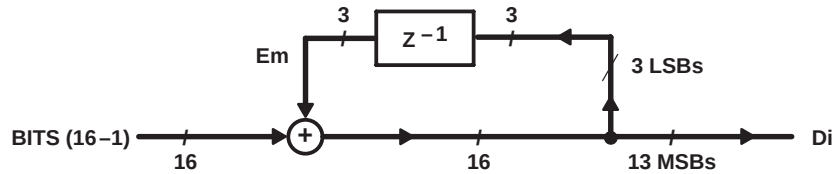


Figure 1. 16- to 13-Bit Modulator at 512-kHz Sampling Rate

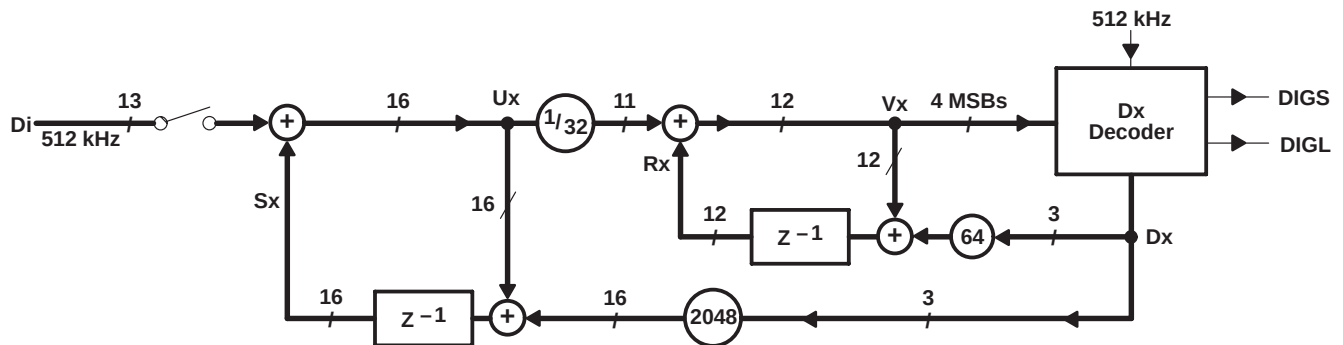


Figure 2. Sigma-Delta-2 Modulator at 512-kHz Sampling Rate

Table 1. Dx Decoder

DECODER INPUT				DECODER OUTPUT				
Vx (11)	Vx (10)	Vx (9)	Vx (8)	Dx (2)	Dx (1)	Dx (0)	DIGS	DIGL
0	1	X	X	H	H	L	L	H
0	0	1	X	H	H	L	L	H
0	0	0	1	H	H	L	L	H
0	0	0	0	H	H	H	L	L
1	1	1	1	L	L	H	H	L
1	1	1	0	L	H	L	H	H
1	1	0	X	L	H	L	H	H
1	0	X	X	L	H	L	H	H

MSP58C20
AUDIO-BAND CONVERTER

SPSS005B-12 MSP58C20 100-Pin SMD Pinout 1996

查询MSP58C20SDW 数据手册

PARAMETER MEASUREMENT INFORMATION

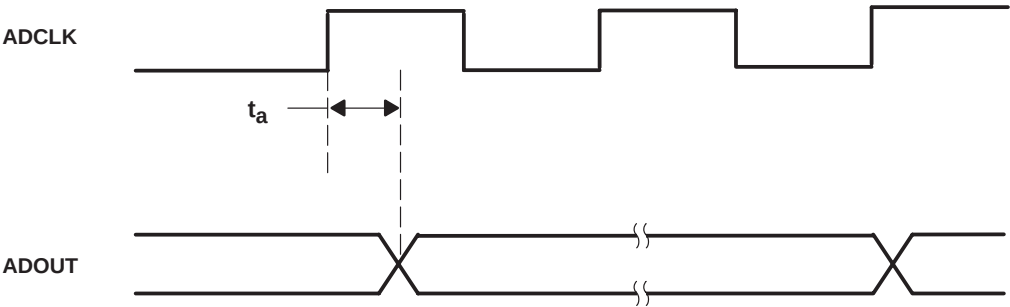


Figure 3. Transmit Access Timing Waveforms

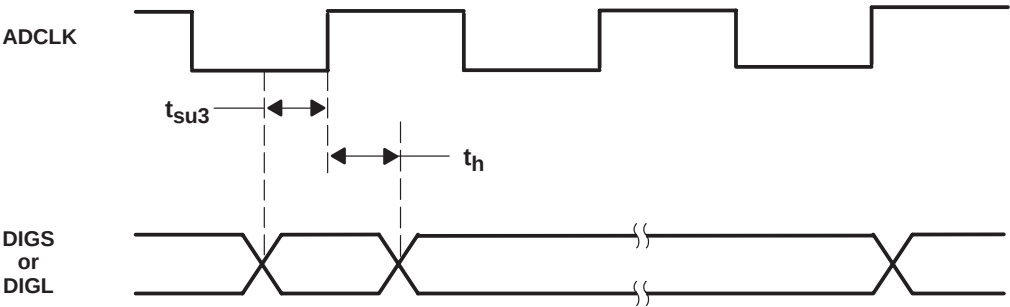


Figure 4. Receive Setup and Hold Time Waveforms

TYPICAL CHARACTERISTICS

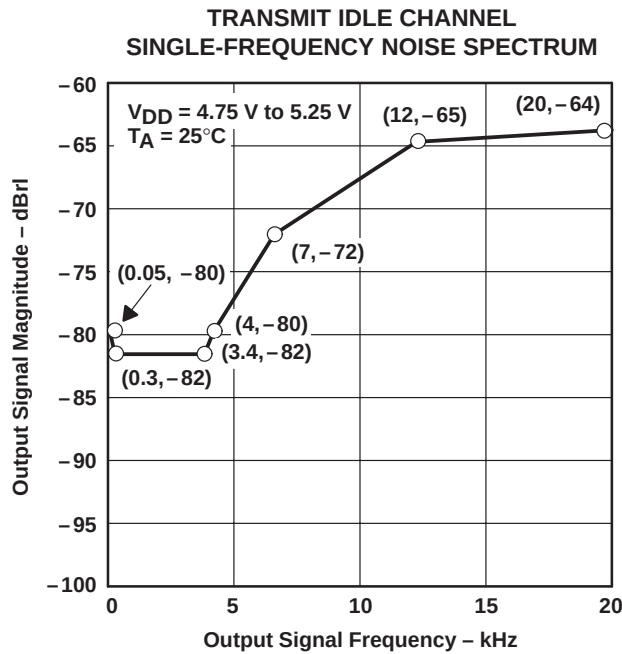
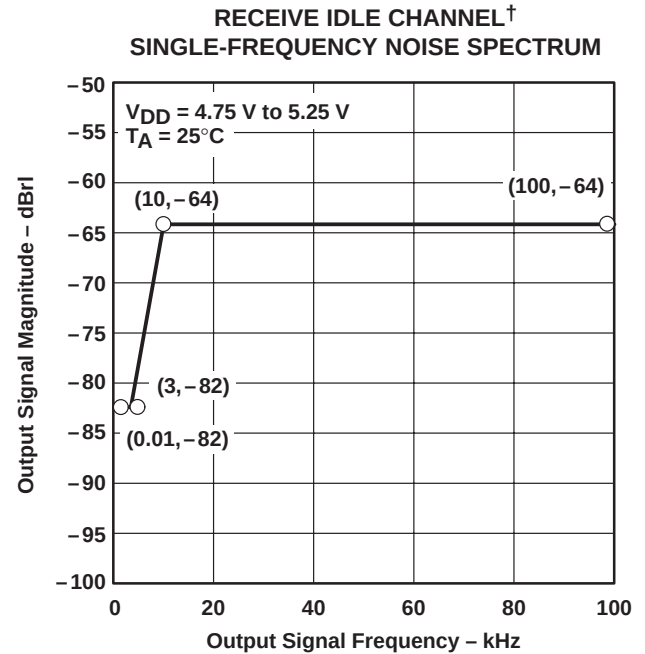
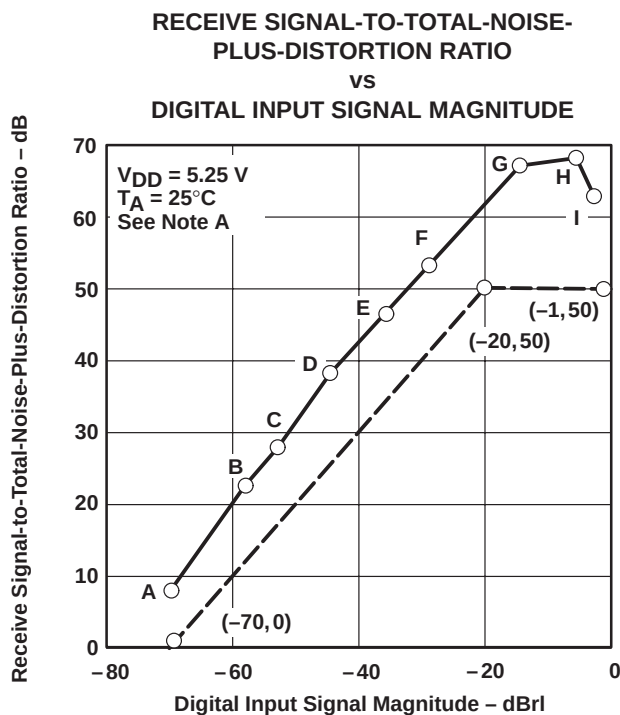


Figure 5



† This parameter is characterized but not tested.

Figure 6



NOTE A: The three points on the dashed line are minimum qualification standards, which every MSP58C20 must pass. The curve shows empirical data from a representative lot.

SET OF POINTS	LOCATION
A	(-70, 9)
B	(-58, 23)
C	(-53, 28)
D	(-43, 38)
E	(-35, 46)
F	(-28, 53)
G	(-13, 67)
H	(-5, 69)
I	(-1, 64)

Figure 7

MSP58C20
AUDIO-BAND CONVERTER

SPSS033B-11 MSP58C20 110-Pin SSOP Product Data Sheet

TYPICAL CHARACTERISTICS

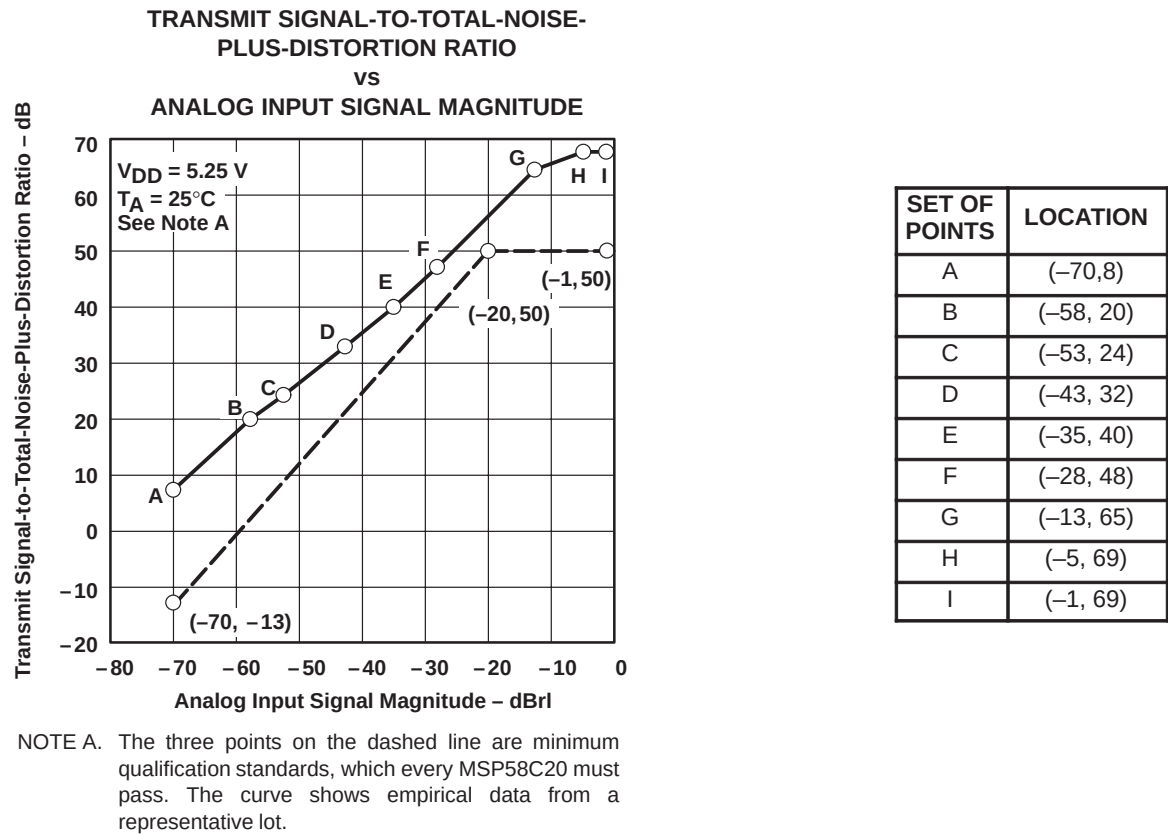
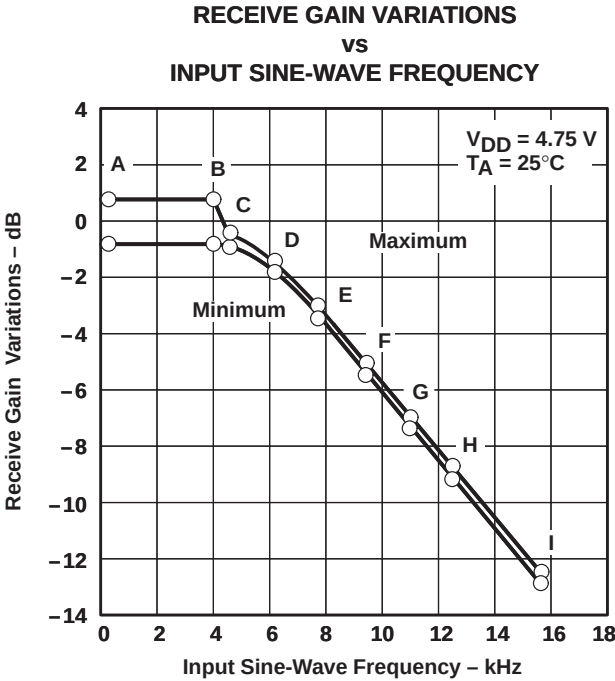


Figure 8

MAXIMUM AND MINIMUM CHARACTERISTICS



SET OF POINTS	MIN	MAX
A	(0.156, -0.6)	(0.156, 0.6)
B	(4, -0.6)	(4, 0.6)
C	(4.6875, -0.7)	(4.6875, -0.4)
D	(6.25, -1.75)	(6.25, -1.4)
E	(7.8125, -3.35)	(7.8125, -2.9)
F	(9.375, -5.25)	(9.375, -4.8)
G	(10.9375, -7.25)	(10.9375, -6.8)
H	(12.5, -9.2)	(12.5, -8.7)
I	(15.625, -12.8)	(15.625, -12.2)

Figure 9

MSP58C20
AUDIO-BAND CONVERTER

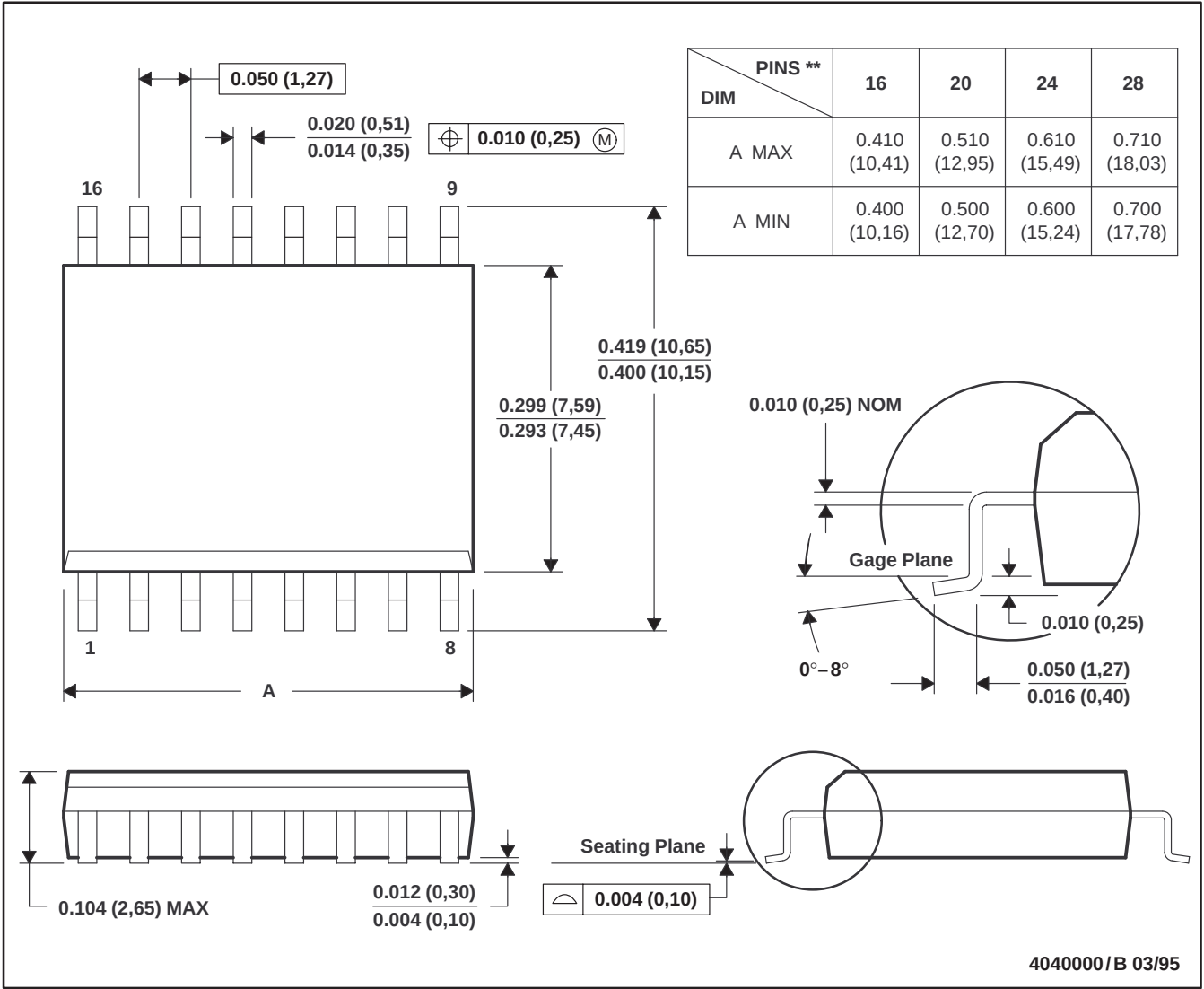
SPSS043B "MSP58C20S1DW" 供应商

MECHANICAL DATA

DW (R-PDSO-G**)

16 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MSP58C20DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
MSP58C20DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
MSP58C20S1DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
MSP58C20S2DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SP58C20DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SP58C20DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

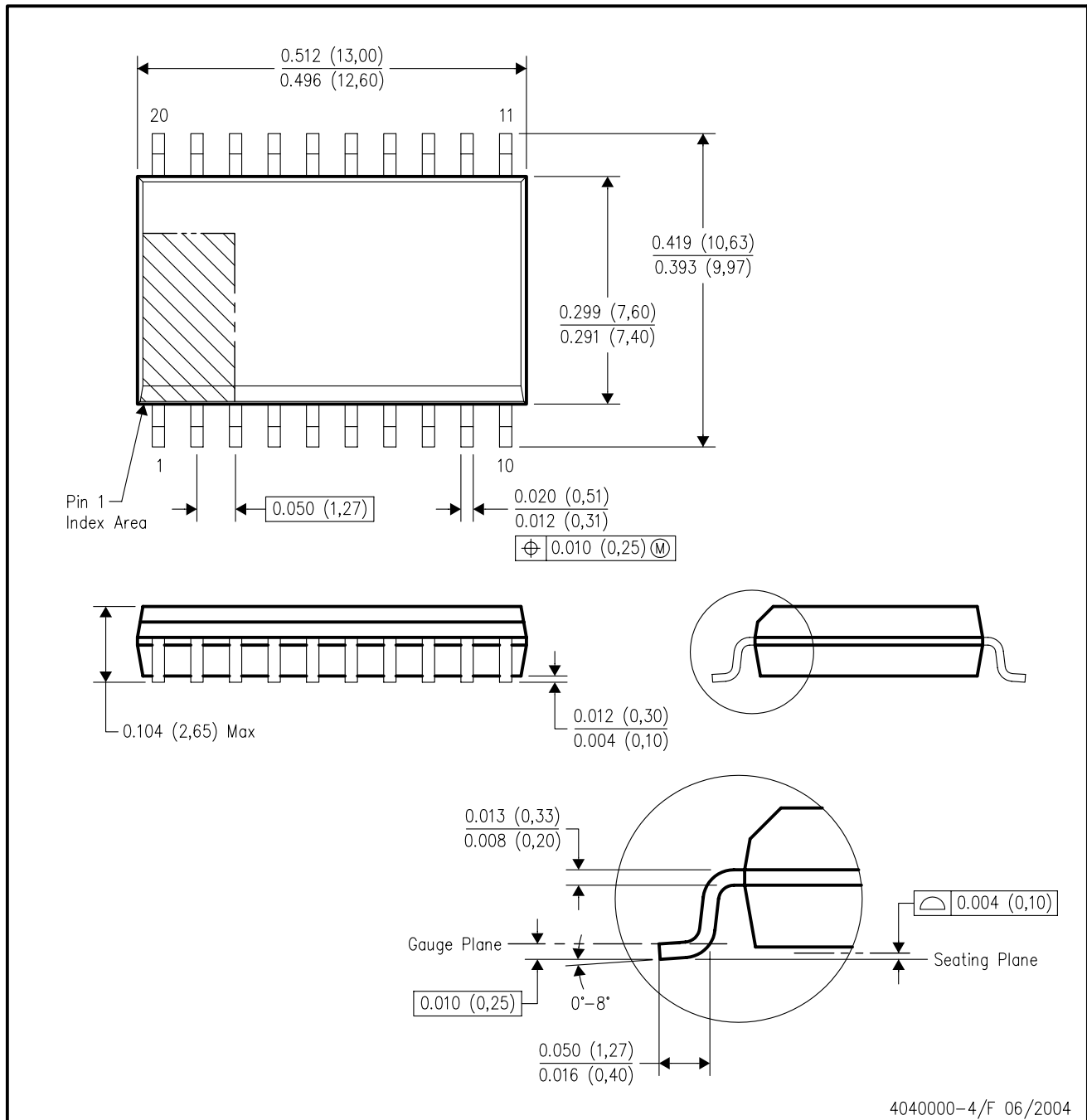
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-013 variation AC.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265